TIDA-00373
Backlight & Smart Lighting Control with Ambient Light sensing

TIV 71333PDQN
LDO
3.3V

5V USB
USB/UART Data

MCU
3.3V

OPT3001
FDC
(Humidity & Temp Sensor)

Backlight Controller

HDC
(Cap-to-Dig. Proximity)

Capacitive Bezel Sensor

LCD Screen

EM Connector

I2C
SPI

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Revision History
Revision | Notes
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Temperature / Humidity Sensor

Ambient Light Sensor

Capacitance-to-Digital Converter

CIN & SHLD Selection Headers
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